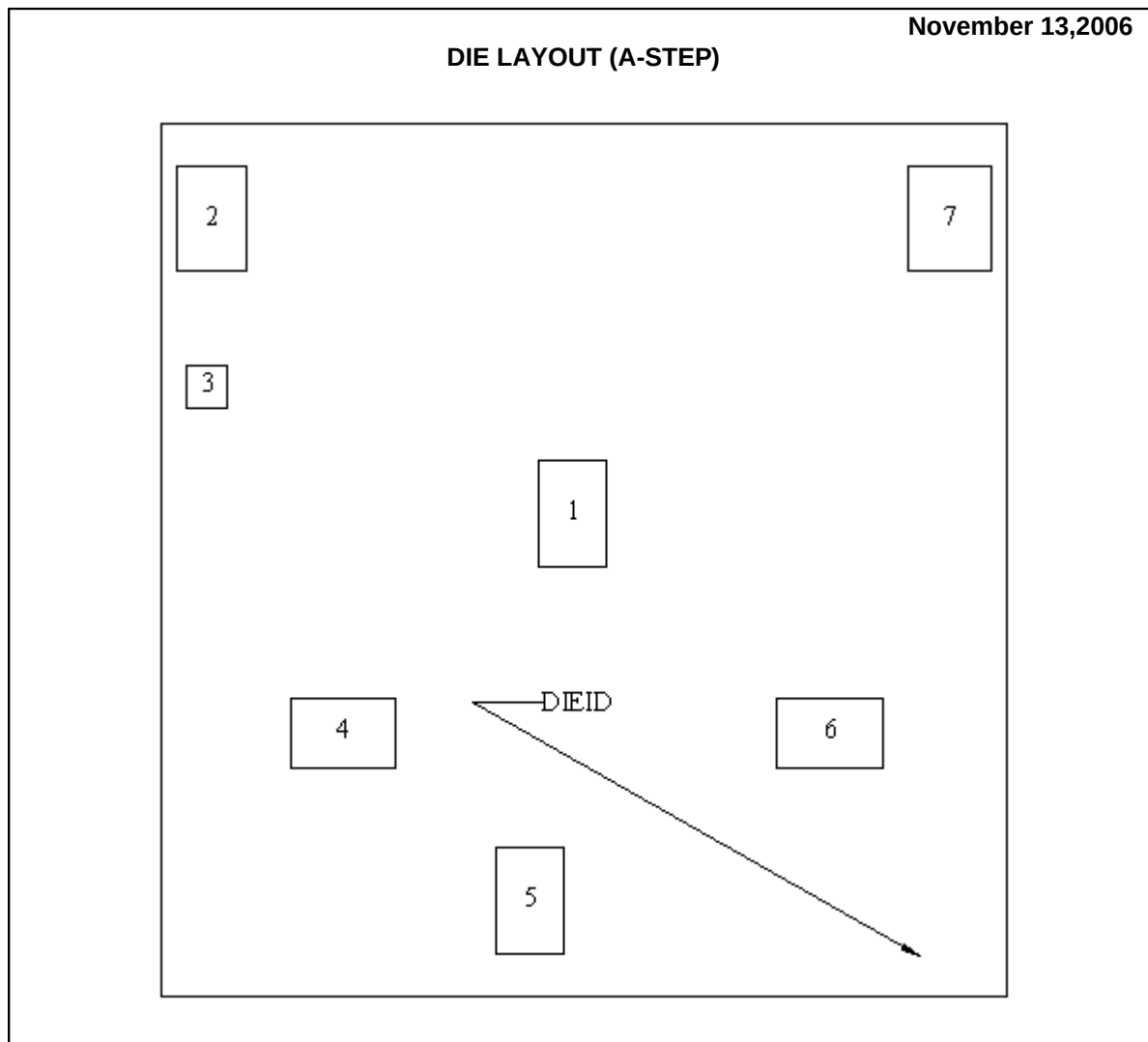


LM150G MD8 MW8
3-AMP ADJUSTABLE REGULATORS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	150A	Bond Pad Opening Size (min)	193µm x 295µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Gold
Die Size (Drawn)	2438µm x 2362µm 96.0mils x 93.0mils	Back Side Connection	OUTPUT
Thickness	254µm Nominal		
Min Pitch	468µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VIN	1	-33	127	193	x	295
ADJ	2	-1041	953	193	x	295
NC	3	-1054	484	117	x	119
OUTPUT	4	-673	-483	295	x	193
VIN	5	-152	-953	193	x	295
OUTPUT	6	686	-483	295	x	193
OUTPUT	7	1022	953	231	x	295

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